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| Orderable: N/A | Designed for: Public Release | Mod. Date: 5/6/2015 |
| TID #: PMP10654 | Project Title: LM5160 Fly-Buck 2-output Module | |
| Number: PMP10654 | Rev: 3 | Sheet Title: |
| SVN Rev: Version control disabled | Assembly Variant: [No Variations] | Sheet: 1 of 2 |
| Drawn By: | File: PMP10654_sch_rev3.SchDoc | Size: B |
| Engineer: X Fang | Contact: http://www.ti.com/support | |

A

A

ZZ1

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

PCB Number: PMP10654
PCB Rev: B

PCB
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B

B

C

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D

D

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|-----------------------------------|--|----------------------|---|
| Orderable: N/A | Designed for: Public Release | Mod. Date: 4/17/2015 |  |
| TID #: PMP10654 | Project Title: LM5160 Fly-Buck 2-output Module | | |
| Number: PMP10654 | Rev: 3 | Sheet Title: | |
| SVN Rev: Version control disabled | Assembly Variant: [No Variations] | Sheet: 2 of 2 | |
| Drawn By: | File: PMP10654_TID_Hardware.SchDoc | Size: B | |
| Engineer: X Fang | Contact: http://www.ti.com/support | | http://www.ti.com © Texas Instruments 2015 |

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